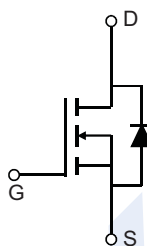
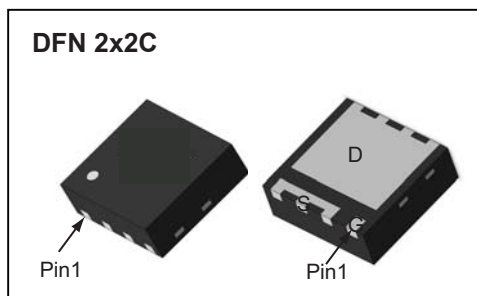


N-Channel MOSFET

AON2392 (KON2392)

■ Features

- $V_{DS} = 100\text{ V}$
- I_D (at $V_{GS} = 10\text{ V}$) = 8 A
- $R_{DS(ON)}$ (at $V_{GS} = 10\text{ V}$) < 32 m Ω
- $R_{DS(ON)}$ (at $V_{GS} = 4.5\text{ V}$) < 39 m Ω

■ Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I_D	$T_A = 25^\circ\text{C}$	8
		$T_A = 70^\circ\text{C}$	6
Pulsed Drain Current ^C	I_{DM}	32	A
Power Dissipation ^B	PD	$T_A = 25^\circ\text{C}$	4.1
		$T_A = 70^\circ\text{C}$	2.6
Thermal Resistance.Junction- to-Ambient ^A	R_{thJA}	$t \leq 10\text{ s}$	30
Thermal Resistance.Junction- to-Ambient ^{AD}		Steady-State	55
Junction Temperature	T_J	150	°C
Storage Temperature Range	T_{stg}	-55 to 150	

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■ Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D = 250\ \mu\text{A}$, $V_{GS} = 0\ \text{V}$	100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 100\ \text{V}$, $V_{GS} = 0\ \text{V}$			1	μA
		$V_{DS} = 100\ \text{V}$, $V_{GS} = 0\ \text{V}$, $T_J = 55^\circ\text{C}$			5	
Gate to Source Leakage Current	I_{GSS}	$V_{DS} = 0\ \text{V}$, $V_{GS} = \pm 20\ \text{V}$			± 100	nA
Gate to Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250\ \mu\text{A}$	1.4		2.4	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10\ \text{V}$, $I_D = 8\ \text{A}$			32	m Ω
		$V_{GS} = 10\ \text{V}$, $I_D = 8\ \text{A}$, $T_J = 125^\circ\text{C}$			57	
		$V_{GS} = 4.5\ \text{V}$, $I_D = 6\ \text{A}$			39	
Forward Transconductance	g_{FS}	$V_{DS} = 5\ \text{V}$, $I_D = 8\ \text{A}$		25		S
Input Capacitance	C_{iss}	$V_{GS} = 0\ \text{V}$, $V_{DS} = 50\ \text{V}$, $f = 1\ \text{MHz}$		840		pF
Output Capacitance	C_{oss}			64		
Reverse Transfer Capacitance	C_{rss}			4		
Gate Resistance	R_g	$V_{GS} = 0\ \text{V}$, $V_{DS} = 0\ \text{V}$, $f = 1\ \text{MHz}$		1.4		Ω
Total Gate Charge	$Q_g(10V)$	$V_{GS} = 10\ \text{V}$, $V_{DS} = 50\ \text{V}$, $I_D = 8\ \text{A}$		12.8	25	nC
Total Gate Charge	$Q_g(4.5V)$			6.1	12	
Gate Source Charge	Q_{gs}			2.1		
Gate Drain Charge	Q_{gd}			1.8		
Output Charge	Q_{oss}		$V_{GS}=0V$, $V_{DS}=50V$		11	
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = 10\ \text{V}$, $V_{DS} = 50\ \text{V}$, $R_L = 5.85\ \Omega$, $R_{GEN} = 3\ \Omega$		7		ns
Turn-On Rise Time	t_r			8		
Turn-Off Delay Time	$t_{d(off)}$			24		
Turn-Off Fall Time	t_f			3		
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 8\ \text{A}$, $di/dt = 500\ \text{A}/\mu\text{s}$		20		nC
Body Diode Reverse Recovery Charge	Q_{rr}			70		
Maximum Body-Diode Continuous Current	I_S				5	A
Diode Forward Voltage	V_{SD}	$V_{GS} = 0\ \text{V}$, $I_S = 1\ \text{A}$			1	V

Notes:

- The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design.
- The power dissipation P_D is based on $T_{J(MAX)}=150^\circ\text{C}$, using $\leq 10\text{s}$ junction-to-case thermal resistance.
- Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^\circ\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ\text{C}$
- The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and case to ambient.
- The static characteristics in Figures 1 to 6 are obtained using $<300\ \mu\text{s}$ pulses, duty cycle 0.5% max.
- These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in² FR-4 board with 2oz Copper, assuming a maximum junction temperature of $T_{J(MAX)}=150^\circ\text{C}$. The SOA curve provides a single pulse rating.

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■ Typical Electrical and Thermal Characteristics

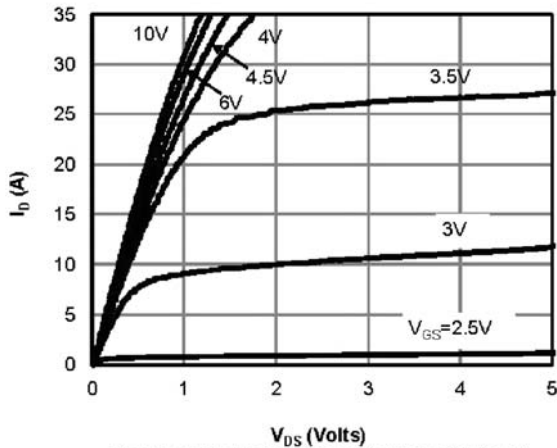


Figure 1: On-Region Characteristics (Note E)

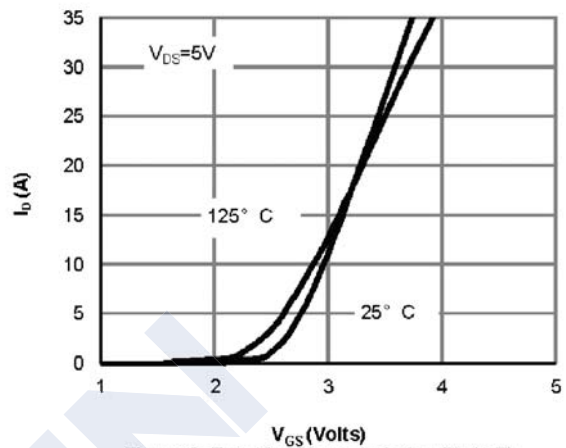


Figure 2: Transfer Characteristics (Note E)

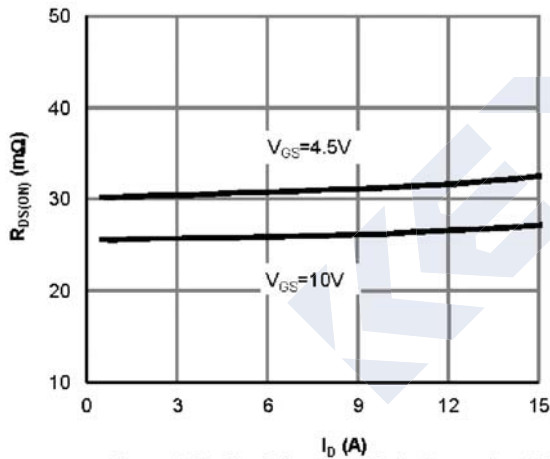


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

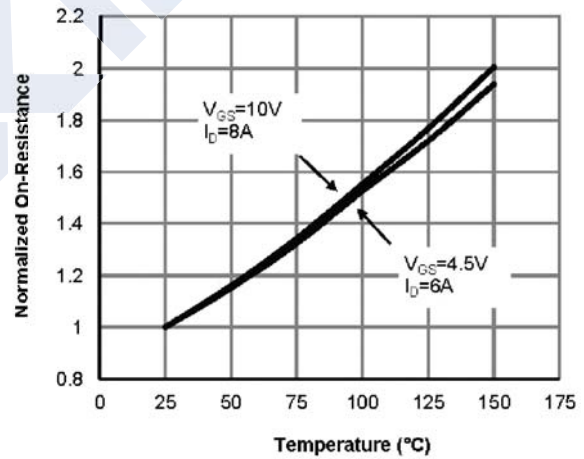


Figure 4: On-Resistance vs. Junction Temperature (Note E)

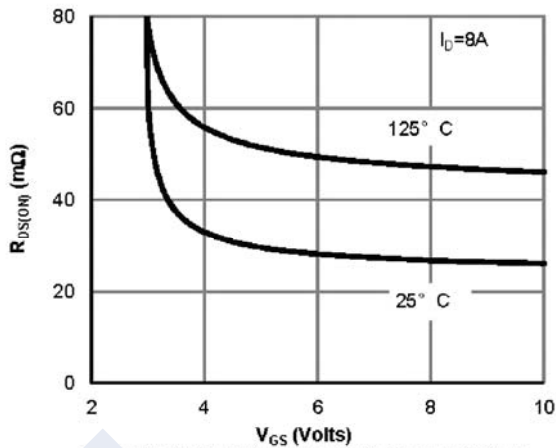


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

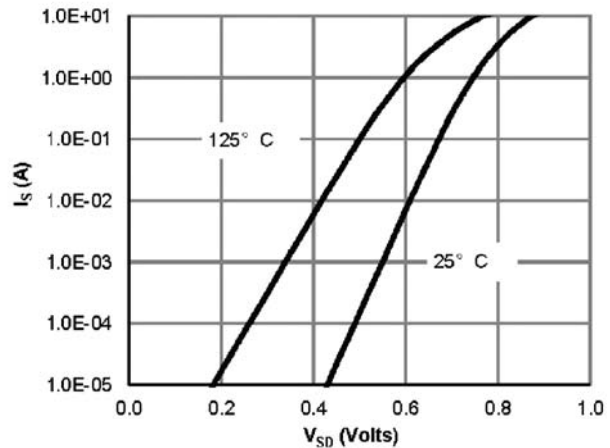


Figure 6: Body-Diode Characteristics (Note E)

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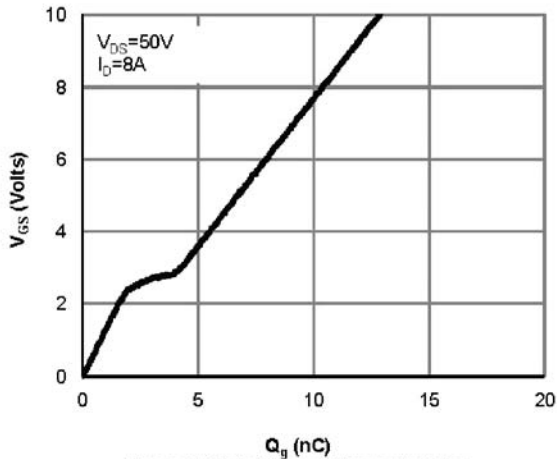


Figure 7: Gate-Charge Characteristics

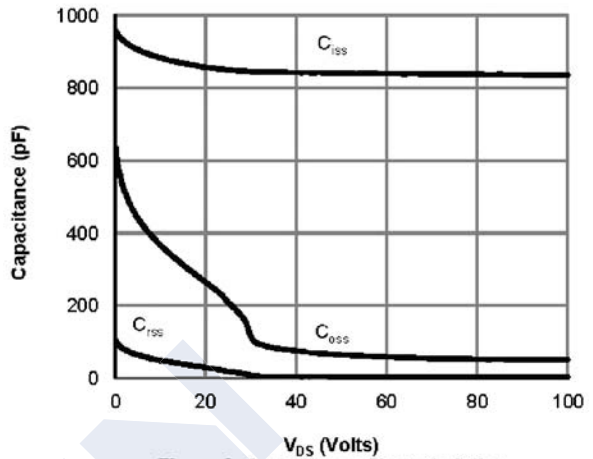


Figure 8: Capacitance Characteristics

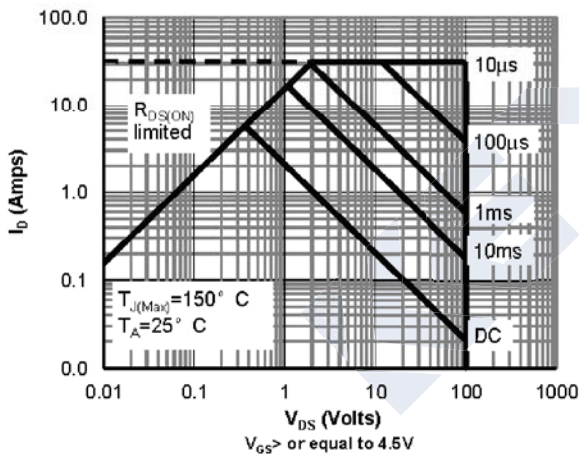


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

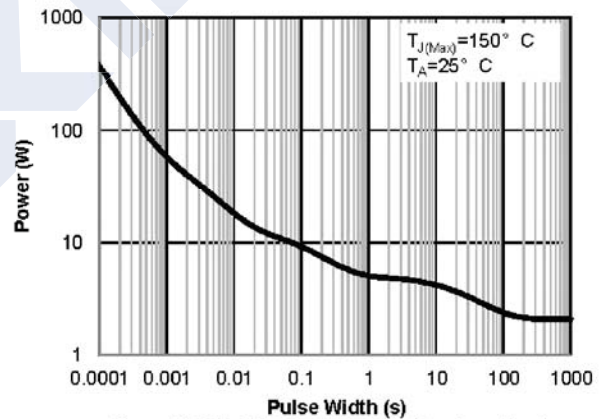


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

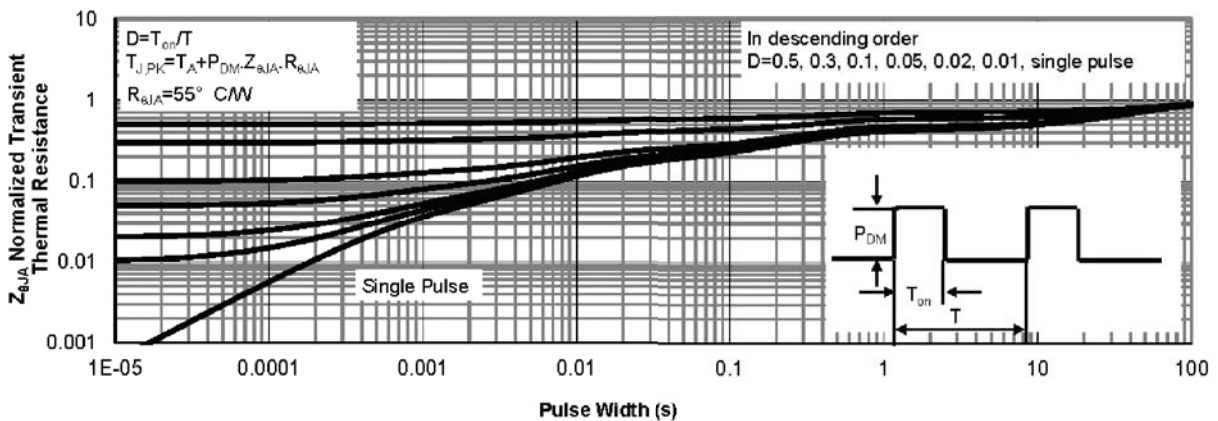


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

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Figure A: Gate Charge Test Circuit & Waveforms

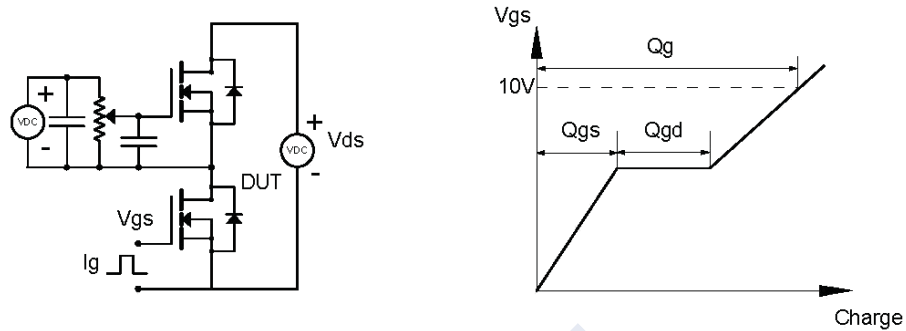


Figure B: Resistive Switching Test Circuit & Waveforms

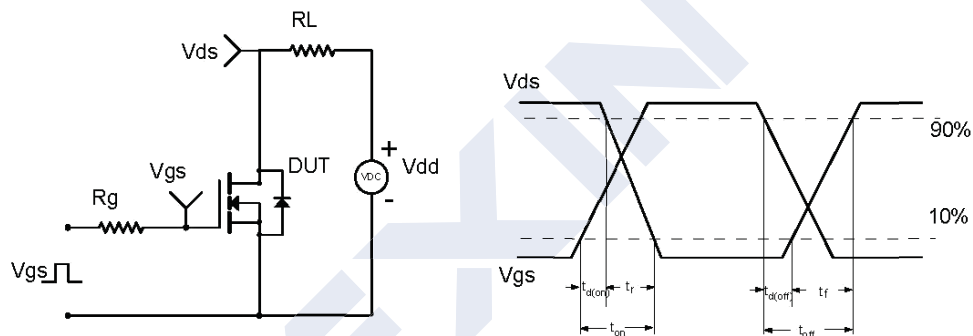


Figure C: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

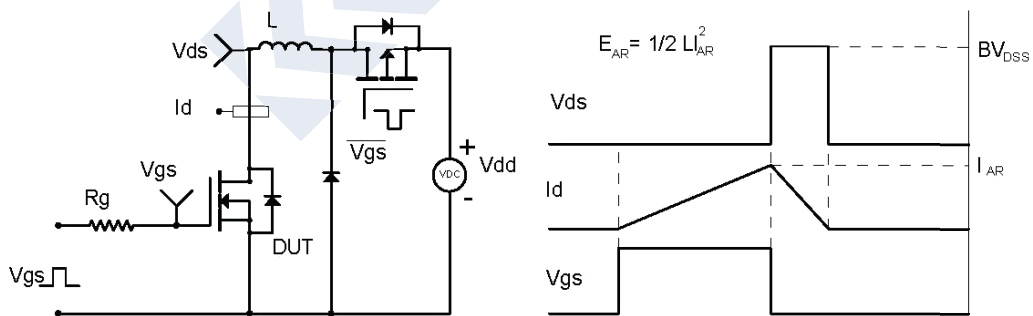


Figure D: Diode Recovery Test Circuit & Waveforms

